

DATA SHEET

BFM505

Dual NPN wideband transistor

Product specification
Supersedes data of 1995 Sep 04

1996 Oct 08



Dual NPN wideband transistor

BFM505

FEATURES

- Small size
- Temperature and h_{FE} matched
- Low noise and high gain
- High gain at low current and low capacitance at low voltage
- Gold metallization ensures excellent reliability.

APPLICATIONS

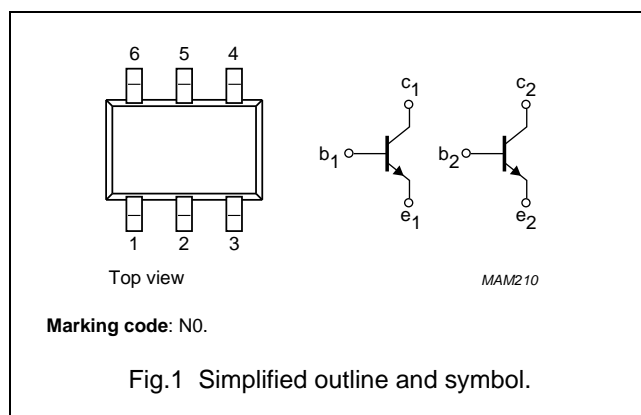
- Oscillator and buffer amplifiers
- Balanced amplifiers
- LNA/mixer.

DESCRIPTION

Dual transistor with two silicon NPN RF dies in a surface mount, 6-pin SOT363 (S-mini) package. The transistors are primarily intended for wideband applications in the GHz-range in the RF front end of analog and digital cellular phones, cordless phones, radar detectors, pagers and satellite TV-tuners.

PINNING - SOT363A

PIN	SYMBOL	DESCRIPTION
1	b ₁	base 1
2	e ₁	emitter 1
3	c ₂	collector 2
4	b ₂	base 2
5	e ₂	emitter 2
6	c ₁	collector 1



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Any single transistor						
C _{re}	feedback capacitance	I _e = 0; V _{CB} = 3 V; f = 1 MHz	–	0.22	–	pF
f _T	transition frequency	I _C = 5 mA; V _{CE} = 3V; f = 1 GHz	–	9	–	GHz
S ₂₁ ²	insertion power gain	I _C = 5 mA; V _{CE} = 3 V; f = 900 MHz; T _{amb} = 25 °C	14	15	–	dB
G _{UM}	maximum unilateral power gain	I _C = 5 mA; V _{CE} = 3 V; f = 900 MHz; T _{amb} = 25 °C	–	17	–	dB
F	noise figure	I _C = 1 mA; V _{CE} = 3 V; f = 900 MHz; Γ _S = Γ _{opt}	–	1.1	1.6	dB
R _{th j-s}	thermal resistance from junction to soldering point	single loaded	–	–	230	K/W
		double loaded	–	–	115	K/W

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LIMITING VALUES

In accordance with the Absolute Maximum System IEC 134.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Any single transistor					
V _{CBO}	collector-base voltage	open emitter	–	20	V
V _{CEO}	collector-emitter voltage	open base	–	8	V
V _{EBO}	emitter-base voltage	open collector	–	2.5	V
I _C	DC collector current		–	18	mA
P _{tot}	total power dissipation	up to T _s = 118 °C; note 1	–	500	mW
T _{stg}	storage temperature		–65	+175	°C
T _j	junction temperature		–	175	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point; note 1	single loaded	230	K/W
		double loaded	115	K/W

Note to the Limiting values and Thermal characteristics

1. T_s is the temperature at the soldering point of the collector pin.

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CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

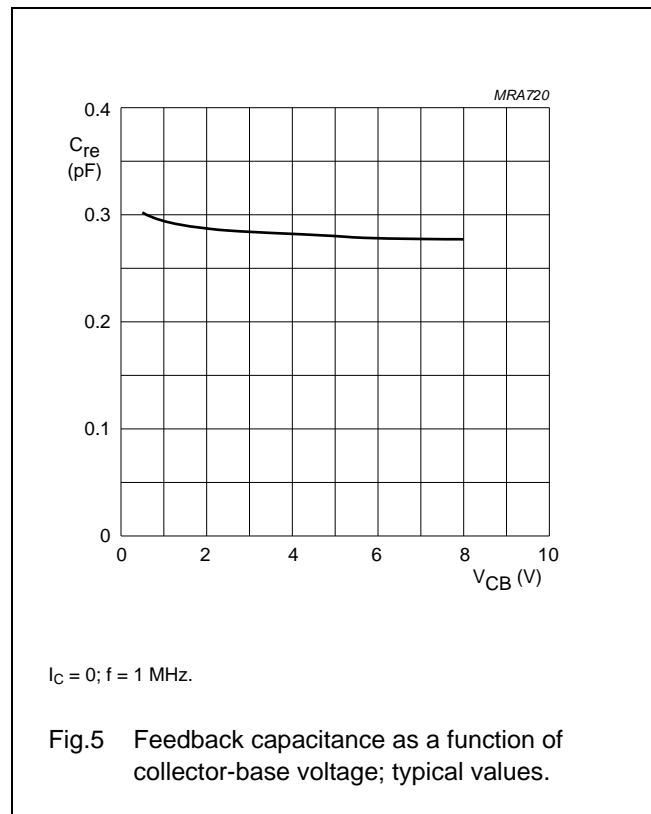
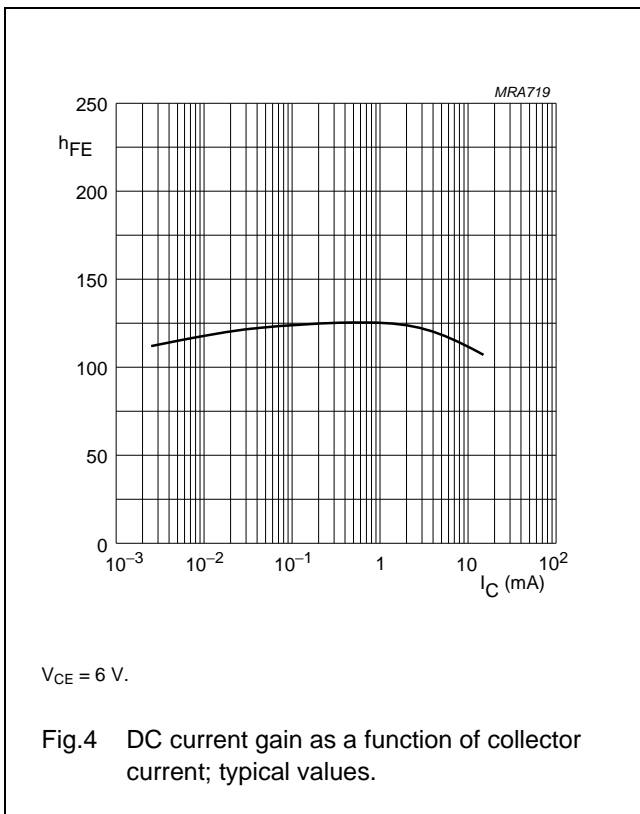
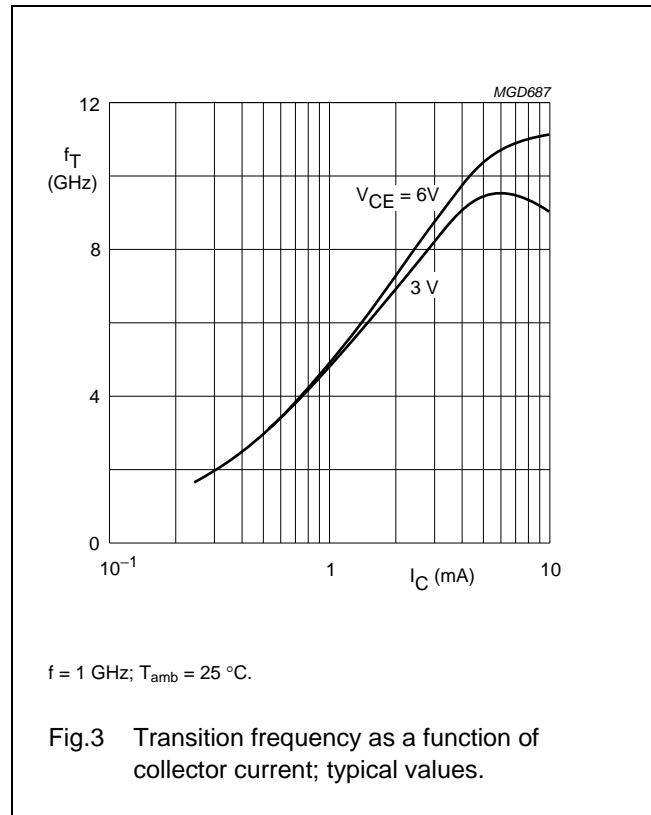
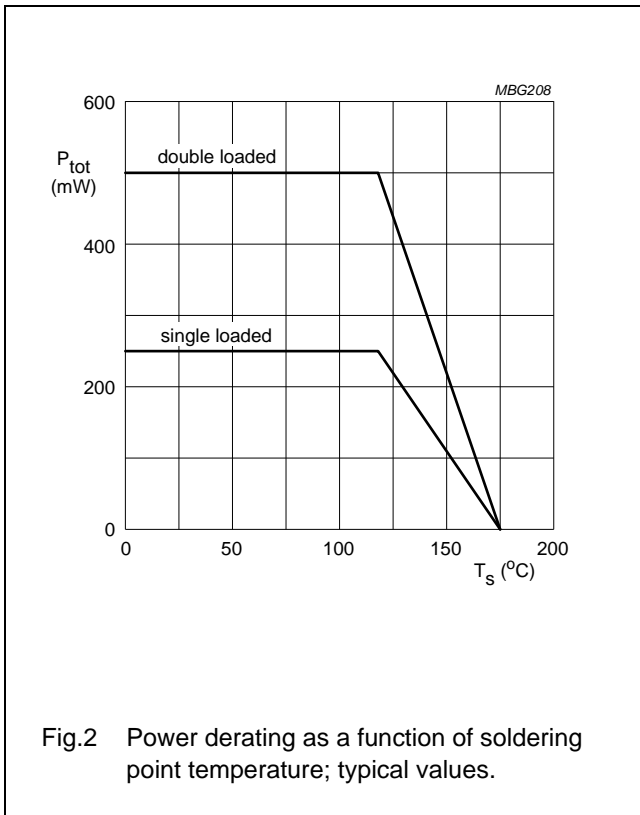
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
DC characteristics of any single transistor						
$V_{(BR)CBO}$	collector-base breakdown voltage	$I_C = 2.5\ \mu\text{A}; I_E = 0$	20	–	–	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	$I_C = 10\ \mu\text{A}; I_B = 0$	8	–	–	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	$I_E = 2.5\ \mu\text{A}; I_C = 0$	2.5	–	–	V
I_{CBO}	collector-base leakage current	$V_{CB} = 6\ \text{V}; I_E = 0$	–	–	50	nA
h_{FE}	DC current gain	$I_C = 5\ \text{mA}; V_{CE} = 6\ \text{V}$	60	120	250	
DC characteristics of the dual transistor						
Δh_{FE}	ratio of highest and lowest DC current gain	$I_{C1} = I_{C2} = 5\ \text{mA}; V_{CE1} = V_{CE2} = 6\ \text{V}$	1	1.2	–	
ΔV_{BEO}	difference between highest and lowest base-emitter voltage (offset voltage)	$I_{E1} = I_{E2} = 10\ \text{mA}; T_{\text{amb}} = 25\text{ °C}$	0	1	–	mV
AC characteristics of any single transistor						
f_T	transition frequency	$I_C = 5\ \text{mA}; V_{CE} = 3\ \text{V}; f = 1\ \text{GHz}$	–	9	–	GHz
C_c	collector capacitance	$I_E = i_e = 0; V_{CB} = 3\ \text{V}; f = 1\ \text{MHz}$	–	0.31	–	pF
C_{re}	feedback capacitance	$I_C = 0; V_{CB} = 3\ \text{V}; f = 1\ \text{MHz}$	–	0.22	–	pF
G_{UM}	maximum unilateral power gain; note 1	$I_C = 5\ \text{mA}; V_{CE} = 3\ \text{V}; T_{\text{amb}} = 25\text{ °C}; f = 900\ \text{MHz}$	–	17	–	dB
		$I_C = 5\ \text{mA}; V_{CE} = 3\ \text{V}; T_{\text{amb}} = 25\text{ °C}; f = 2\ \text{GHz}$	–	10	–	dB
$ s_{21} ^2$	insertion power gain	$I_C = 5\ \text{mA}; V_{CE} = 3\ \text{V}; f = 900\ \text{MHz}; T_{\text{amb}} = 25\text{ °C}$	14	15	–	dB
F	noise figure	$I_C = 5\ \text{mA}; V_{CE} = 3\ \text{V}; f = 900\ \text{MHz}; \Gamma_S = \Gamma_{\text{opt}}$	–	1.4	1.8	dB
		$I_C = 5\ \text{mA}; V_{CE} = 3\ \text{V}; f = 2\ \text{GHz}; \Gamma_S = \Gamma_{\text{opt}}$	–	1.9	–	dB
		$I_C = 1\ \text{mA}; V_{CE} = 3\ \text{V}; f = 900\ \text{MHz}; \Gamma_S = \Gamma_{\text{opt}}$	–	1.1	1.6	dB

Note

1. G_{UM} is the maximum unilateral power gain, assuming s_{12} is zero. $G_{UM} = 10 \log \frac{|s_{21}|^2}{(1 - |s_{11}|^2)(1 - |s_{22}|^2)}$ dB

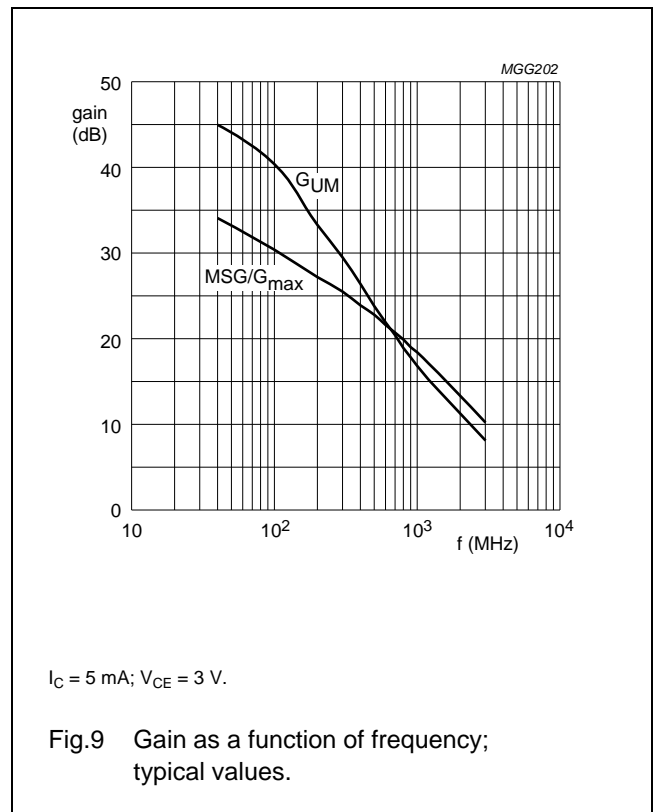
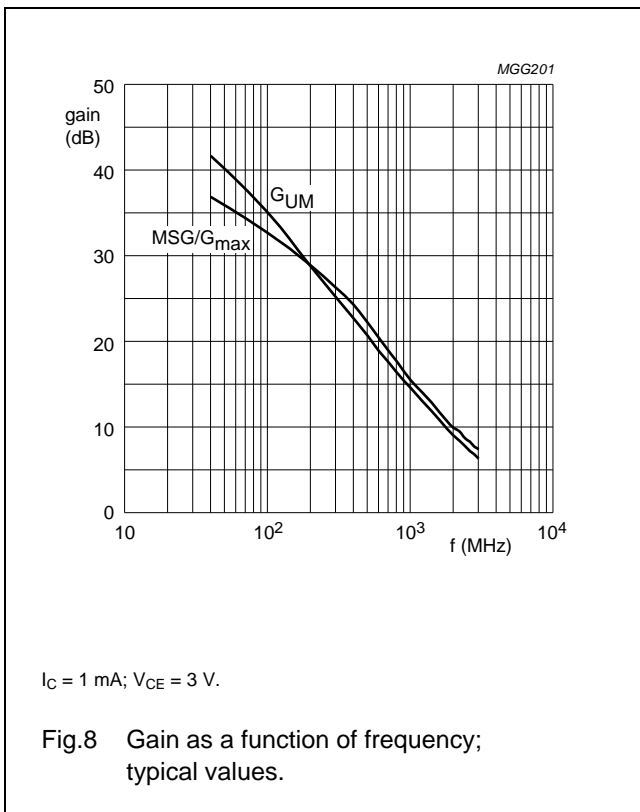
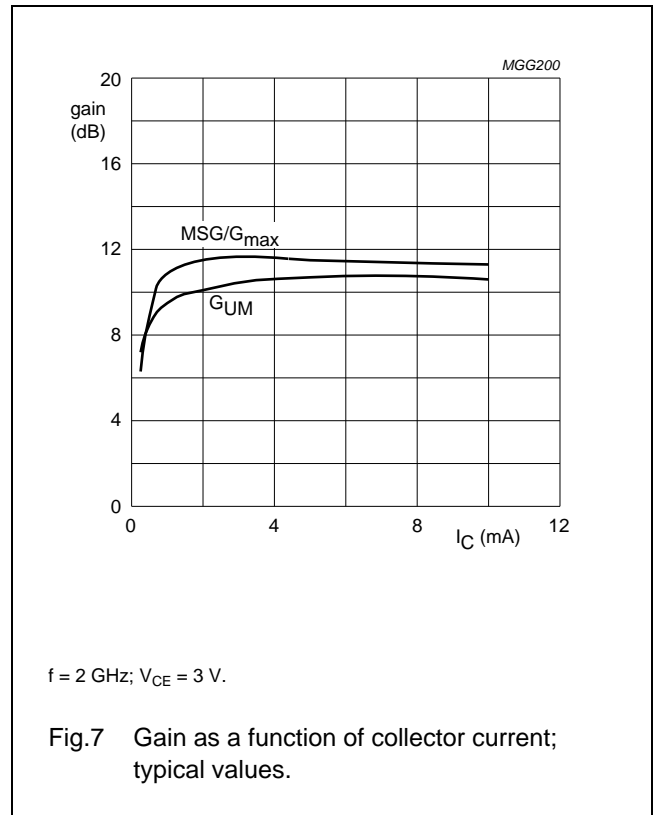
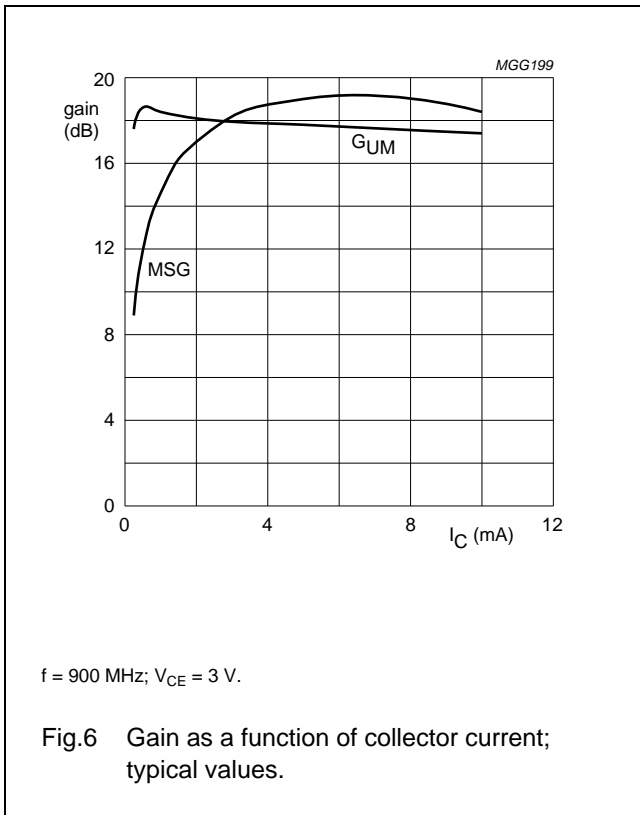
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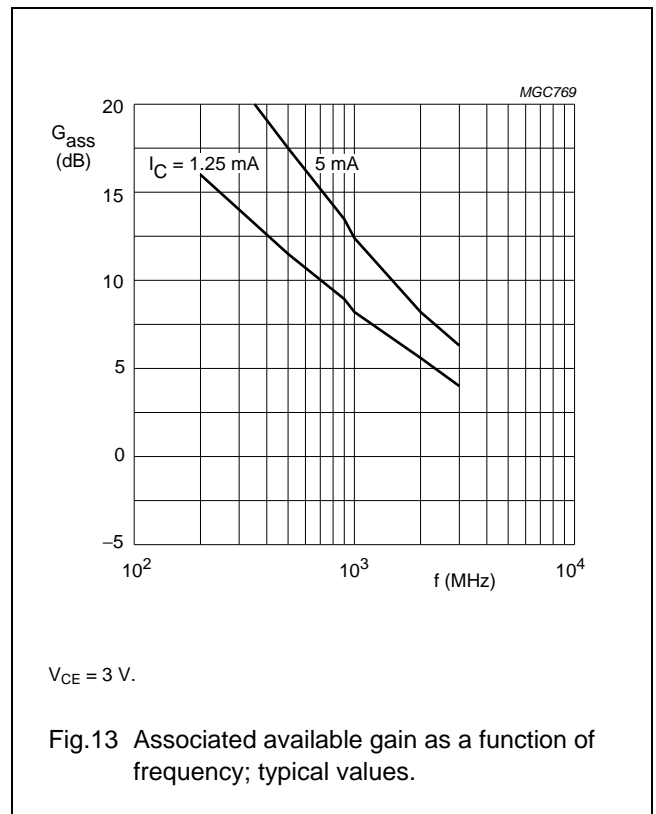
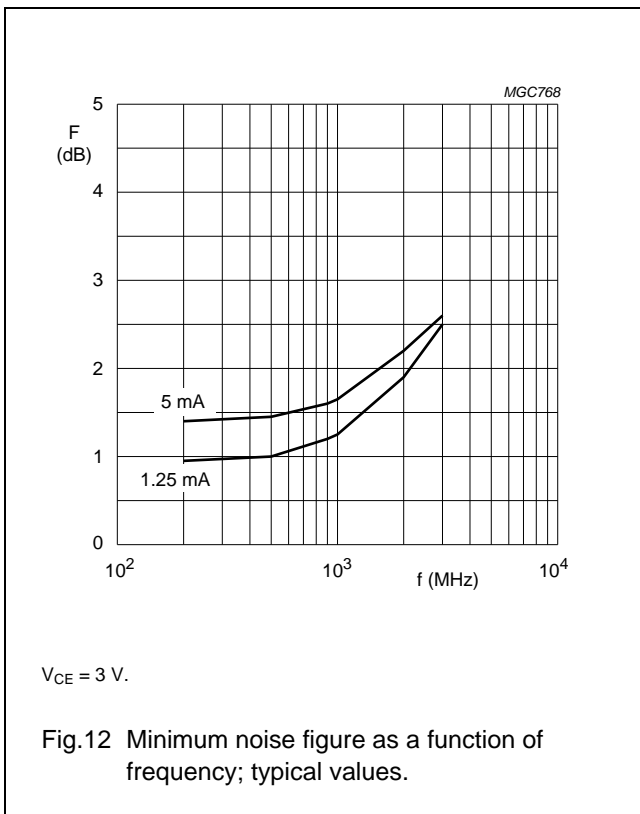
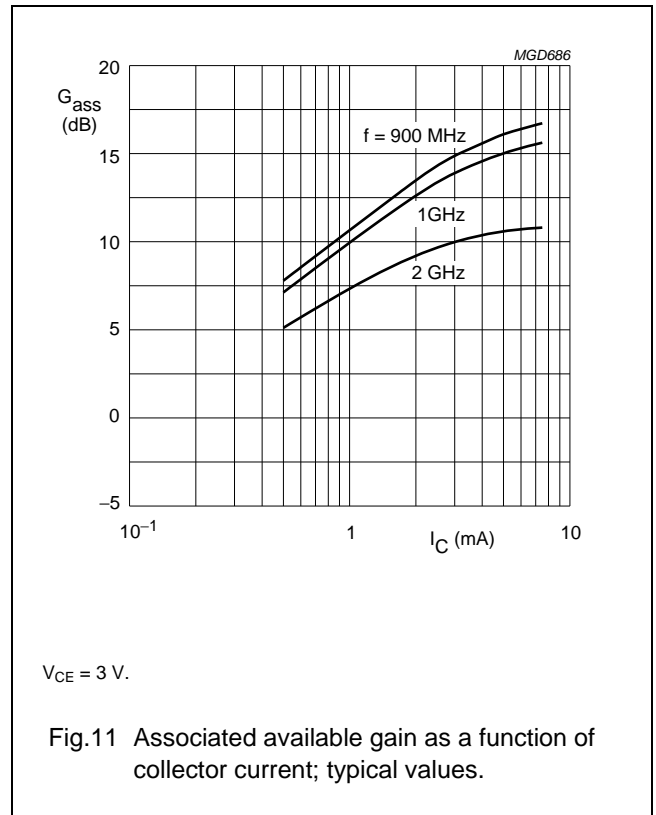
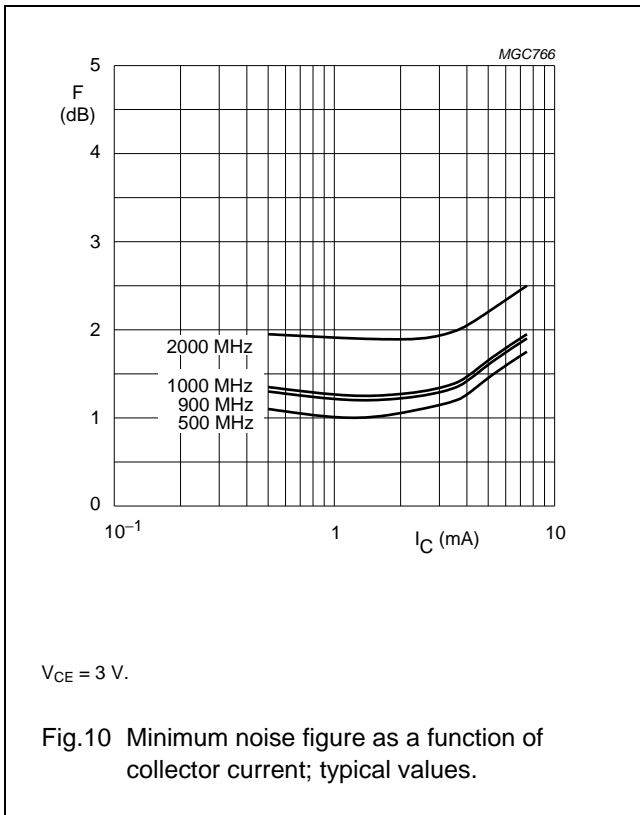
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APPLICATION INFORMATION

SPICE parameters for any single BFM505 die

SEQUENCE No.	PARAMETER	VALUE	UNIT
1	IS	134.1	aA
2	BF	180.0	–
3	NF	0.988	–
4	VAF	38.34	V
5	IKF	150.0	mA
6	ISE	27.81	fA
7	NE	2.051	–
8	BR	55.19	–
9	NR	0.982	–
10	VAR	2.459	V
11	IKR	2.920	mA
12	ISC	17.45	aA
13	NC	1.062	–
14	RB	20.00	Ω
15	IRB	1.000	μA
16	RBM	20.00	Ω
17	RE	1.171	Ω
18	RC	4.350	Ω
19 ⁽¹⁾	XTB	0.000	–
20 ⁽¹⁾	EG	1.110	eV
21 ⁽¹⁾	XTI	3.000	–
22	CJE	284.7	fF
23	VJE	600.0	mV
24	MJE	0.303	–
25	TF	7.037	ps
26	XTF	12.34	–
27	VTF	1.701	V
28	ITF	30.64	mA
29	PTF	0.000	deg
30	CJC	242.4	fF
31	VJC	188.6	mV
32	MJC	0.041	–
33	XCJC	0.130	–
34	TR	1.332	ns
35 ⁽¹⁾	CJS	0.000	F
36 ⁽¹⁾	VJS	750.0	mV
37 ⁽¹⁾	MJS	0.000	–
38	FC	0.897	–

Note

1. These parameters have not been extracted, the default values are shown.

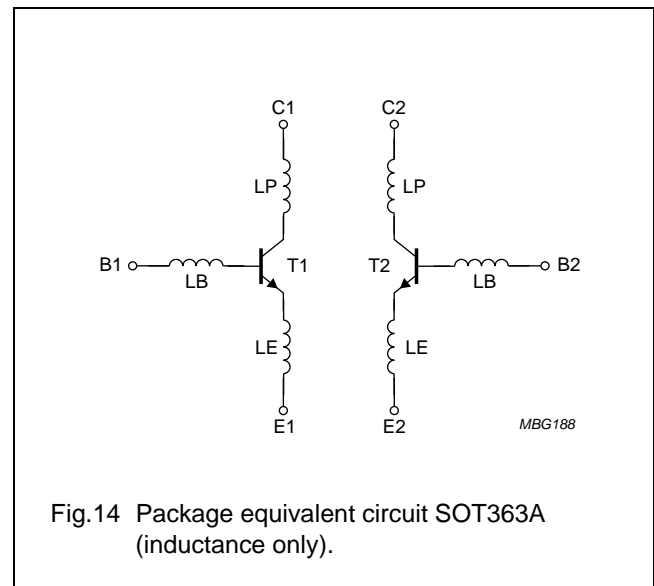


Fig.14 Package equivalent circuit SOT363A (inductance only).

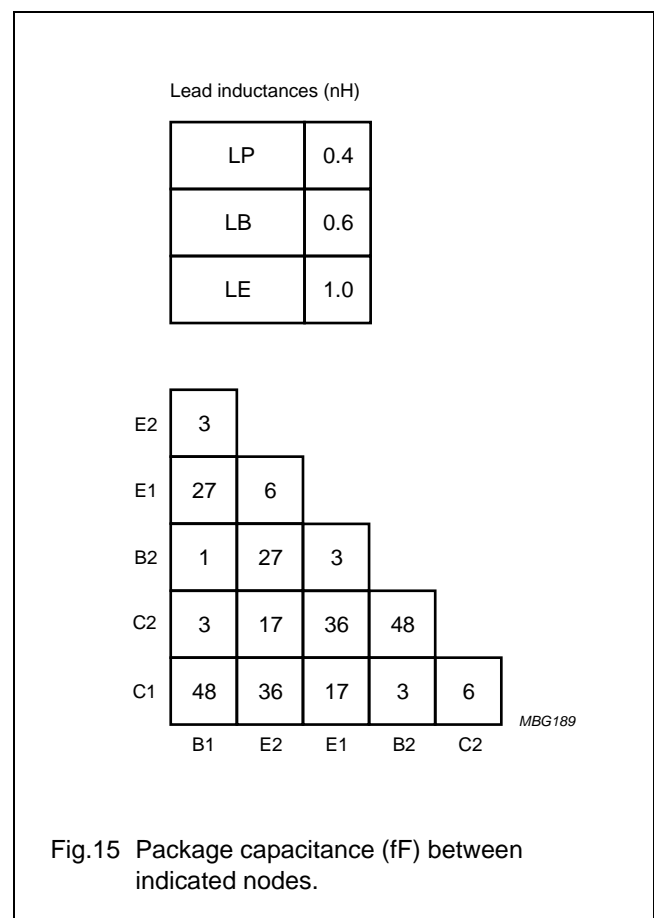


Fig.15 Package capacitance (fF) between indicated nodes.

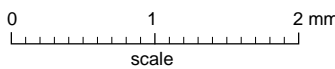
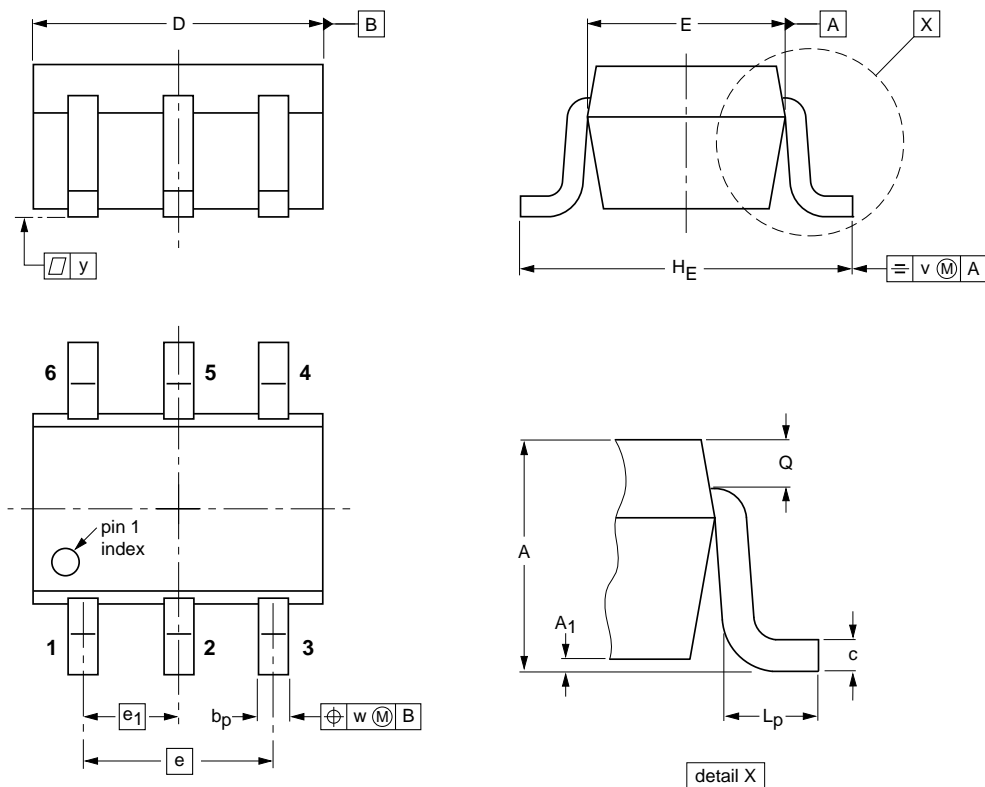
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PACKAGE OUTLINE

Plastic surface-mounted package; 6 leads

SOT363



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w	y
mm	1.1 0.8	0.1	0.30 0.20	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.25 0.15	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT363			SC-88			04-11-08 06-03-16

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: <http://www.nxp.com>

For sales offices addresses send e-mail to: salesaddresses@nxp.com

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